



BIM and Its Integration with Emerging Technologies

Guest Editors:

Prof. Dr. Inhan Kim

Department of Architecture,
Kyunghee University, Seoul
17104, Korea

Dr. Jung In Kim

Department of Architecture and
Civil Engineering, City University
of Hong Kong, Hong Kong
999077, Korea

Deadline for manuscript
submissions:

closed (31 December 2021)

Message from the Guest Editors

Dear Colleagues,

Building information modeling (BIM) has quickly attracted attention in the construction industry due to its promising benefits and has become the key technology affecting all phases of construction projects (i.e., design, construction, operation). BIM also offers a great potential to significantly enhance project performances through its integration with other emerging technologies, such as virtual reality (VR) for improved design inspection, laser scanning for capturing as-built conditions, unmanned aerial vehicles (UAVs) for automated progress monitoring, design for manufacture and assembly (DFMA) for improved productivity, and the Internet of Things (IOT) for post-occupancy evaluation.

This Special Issue invites you to submit a manuscript on all related topics in the form of reviews and original research papers. Topics include but are not limited to the examples addressed above.

Prof. Dr. Inhan Kim

Guest Editor





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q2 (*Engineering, Multidisciplinary*) / CiteScore - Q1 (*General Engineering*)

Contact Us

Applied Sciences Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](https://twitter.com/Applsci)